



THE DATASHEET OF TLC354CD



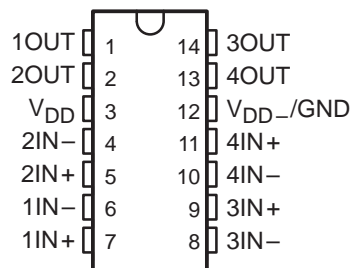
TLC354

LinCMOS™ QUADRUPLE DIFFERENTIAL COMPARATORS

SLCS116B – SEPTEMBER 1985 – REVISED FEBRUARY 1997

- **Single- or Dual-Supply Operation**
- **Wide Range of Supply Voltages**
1.4 V to 18 V
- **Very Low Supply Current Drain**
300 μ A Typ at 5 V
130 μ A Typ at 1.4 V
- **Built-In ESD Protection**
- **High Input Impedance . . . $10^{12} \Omega$ Typ**
- **Extremely Low Input Bias Current**
5 pA Typ
- **Ultrastable Low Input Offset Voltage**
- **Input Offset Voltage Change at Worst-Case Input Conditions Typically 0.23 μ V/Month, Including the First 30 Days**
- **Common-Mode Input Voltage Range Includes Ground**
- **Outputs Compatible With TTL, MOS, and CMOS**
- **Pin-Compatible With LM339**

D, N, OR PW PACKAGE
(TOP VIEW)



symbol (each comparator)



description

This device is fabricated using LinCMOS™ technology and consists of four independent differential voltage comparators; each is designed to operate from a single power supply. Operation from dual supplies is also possible if the difference between the two supplies is 1.4 V to 18 V. Each device features extremely high input impedance (typically greater than $10^{12} \Omega$), which allows direct interface to high-impedance sources. The outputs are n-channel open-drain configurations and can be connected to achieve positive-logic wired-AND relationships. The capability of the TLC354 to operate from a 1.4-V supply makes this device ideal for low-voltage battery applications.

The TLC354 has internal electrostatic discharge (ESD) protection circuits and has been classified with a 2000-V ESD rating tested under MIL-STD-883C, Method 3015. However, care should be exercised in handling this device as exposure to ESD may result in degradation of the device parametric performance.

The TLC354C is characterized for operation from 0°C to 70°C. The TLC354I is characterized for operation over the industrial temperature range of -40° to 85°C. The TLC354M is characterized for operation over the full military temperature range -55°C to 125°C.

AVAILABLE OPTIONS

T _A	V _{IO} max AT 25°C	PACKAGED DEVICES			CHIP FORM (Y)
		SMALL OUTLINE (D)	PLASTIC DIP (P)	TSSOP (PW)	
0°C to 70°C	5 mV	TLC354CD	TLC354CN	TLC354CPW	TLC354Y
-40°C to 85°C	5 mV	TLC354ID	TLC354IN	—	—
-55°C to 125°C	5 mV	TLC354MD	TLC354MN	—	—

The D packages are available taped and reeled. Add R suffix to device type (e.g., TLC354CDR).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinCMOS is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



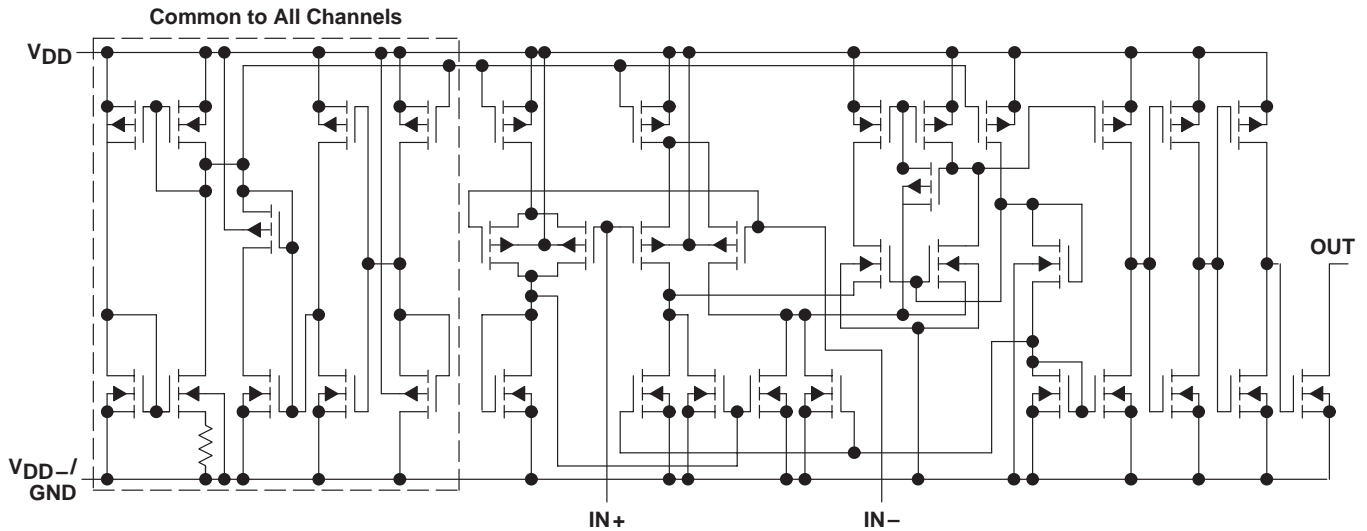
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1997, Texas Instruments Incorporated

TLC354 LinCMOS™ QUADRUPLE DIFFERENTIAL COMPARATORS

SLCS116B – SEPTEMBER 1985 – REVISED FEBRUARY 1997

equivalent schematic (each comparator)



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{DD} (see Note 1)	18 V
Differential input voltage, V_{ID} (see Note 2)	± 18 V
Input voltage, V_I	V_{DD}
Input voltage range, V_I	-0.3 V to 18 V
Output voltage, V_O	18 V
Input current, I_I	± 5 mA
Output current, I_O	20 mA
Duration of output short circuit to ground (see Note 3)	Unlimited
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A : TLC354C	0°C to 70°C
TLC354I	-40°C to 85°C
TLC354M	-55°C to 125°C
Storage temperature range	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values except differential voltages are with respect to network ground.
 2. Differential voltages are at IN+ with respect to IN-.
 3. Short circuits from outputs to V_{DD} can cause excessive heating and eventual device destruction.

DISSIPATION RATING TABLE

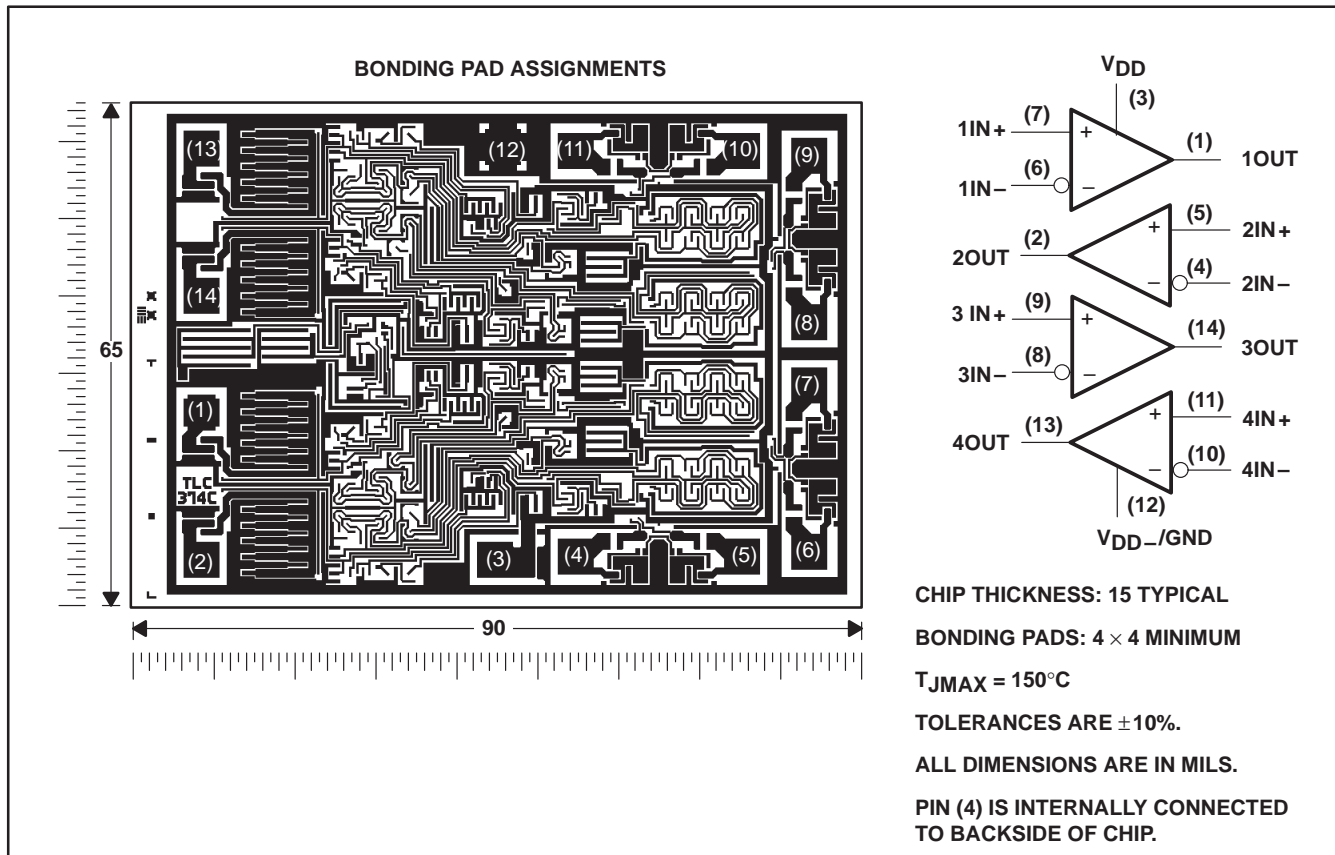
PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D	500 mW	7.6 mW/°C	84°C	500 mW	494 mW	190 mW
N	500 mW	9.2 mW/°C	96°C	500 mW	500 mW	230 mW
PW	700 mW	5.6 mW/°C	25°C	448 mW	N/A	N/A



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TLC364Y chip information

This chip, when properly assembled, displays characteristics similar to the TLC354C. Thermal compression or ultrasonic bonding can be used on the doped-aluminum bonding pads. Chips can be mounted with conductive epoxy or a gold-silicon preform.



recommended operating conditions

	TLC354C		TLC354I	
	MIN	MAX	MIN	MAX
Supply voltage, V _{DD}	1.4	16	1.4	16
	0	0.2	0	0.2
Common-mode input voltage, V _{IC}	0	3.5	0	3.5
	0	8.5	0	8.5
Operating free-air temperature, T _A	0	70	-40	85

V_{DD} = 1.4 VV_{DD} = 5 VV_{DD} = 10 V

electrical characteristics at specified free-air temperature, V_{DD} = 1.4 V

PARAMETER	TEST CONDITIONS	T _A [†]	TLC354C			TLC354I		
			MIN	TYP	MAX	MIN	TYP	MAX
V _{IO} Input offset voltage	V _{IC} = V _{ICRmin} , See Note 4	25°C	2	5	2	2	5	
		Full range		6.5			7	
I _{IO} Input offset current		25°C	1		1	1		
I _{IB} Input bias current		MAX		0.3			1	
		25°C	5		5		1	
V _{ICR} Common-mode input voltage range		MAX		0.6			2	
		25°C	0 to 0.2			0 to 0.2		
I _{OH} High-level output current	V _{ID} = 1 V V _{OH} = 5 V V _{OH} = 15 V	25°C	0.1		0.1		0.1	
		Full range		1			1	
V _{OL} Low-level output voltage	V _{ID} = -0.5 V, I _{OL} = 0.6 mA	25°C	100	200	100	200	200	
		Full range		200			200	
I _{OL} Low-level output current	V _{ID} = -0.5 V, V _{OL} = 300 mV	25°C	1	1.6	1	1.6	1	
		Full range		130			300	
I _{DD} Supply current (four comparators)	V _{ID} = 0.5 V, No load	25°C	130	300	130	300	400	
		Full range		400			400	

[†] All characteristics are measured with zero common-mode input voltage unless otherwise noted. Full range is 0°C to 70°C for TLC354C, -40°C to 85°C to 125°C for the TLC354M. MAX is 70°C for TLC354C, 85°C TLC354I, and 125°C for the TLC354M. IMPORTANT: See Parameter Measurement Information. NOTE 4: The offset voltage limits given are the maximum values required to drive the output above 1.25 V or below 150 mV with a 10-kΩ resistor between the output and ground. The offset voltage limits can be verified by applying the limit value to the input and checking for the appropriate output state.

TLC354 LinCMOS™ QUADRUPLE DIFFERENTIAL COMPARATORS

SLCS116B – SEPTEMBER 1985 – REVISED FEBRUARY 1997

electrical characteristics at specified free-air temperature, $V_{DD} = 1.4\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLC354Y			UNIT
		MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_{IC} = V_{ICR} \text{ min, See Note 4}$		2	5	mV
I_{IO} Input offset current			1		pA
I_{IB} Input bias current			5		pA
V_{ICR} Common-mode input voltage range		0 to 0.2			V
I_{OH} High-level output current	$V_{ID} = 1\text{ V, } V_{OH} = 5\text{ V}$		0.1		nA
V_{OL} Low-level output voltage	$V_{ID} = -0.5\text{ V, } I_{OL} = 0.6\text{ mA}$		100	200	mV
I_{OL} Low-level output current	$V_{ID} = -0.5\text{ V, } V_{OL} = 300\text{ mV}$	1	1.6		mA
I_{DD} Supply current (four comparators)	$V_{ID} = 0.5\text{ V, No load}$		130	300	μA

NOTE 4: The offset voltage limits given are the maximum values required to drive the output above 1.25 V or below 150 mV with a 10-k Ω resistor between the output and V_{DD} . They can be verified by applying the limit value to the input and checking for the appropriate output state.

electrical characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLC354Y			UNIT
		MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_{IC} = V_{ICR} \text{ min, See Note 5}$		2	5	mV
I_{IO} Input offset current			1		pA
I_{IB} Input bias current			5		pA
V_{ICR} Common-mode input voltage range		0 to $V_{DD}-1$			V
I_{OH} High-level output current	$V_{ID} = 1\text{ V, } V_{OH} = 5\text{ V}$		0.1		nA
V_{OL} Low-level output voltage	$V_{ID} = -1\text{ V, } I_{OL} = 4\text{ mA}$		150	400	mV
I_{OL} Low-level output current	$V_{ID} = -1\text{ V, } V_{OL} = 1.5\text{ mV}$	6	16		mA
I_{DD} Supply current (four comparators)	$V_{ID} = 1\text{ V, No load}$		0.3	0.6	mA

NOTE 5: The offset voltage limits given are the maximum values required to drive the output above 4 V or below 400 mV with a 10-k Ω resistor between the output and V_{DD} . They can be verified by applying the limit value to the input and checking for the appropriate output state.

switching characteristics, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TLC354Y			UNIT
		MIN	TYP	MAX	
Response time	R_L connected to 5 V through 5.1 k Ω , $C_L = 15\text{ pF}^\ddagger$, See Note 6	100-mV input step with 5-mV overdrive			ns
		TTL-level input step			

$^\ddagger C_L$ includes probe and jig capacitance.

NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



PARAMETER MEASUREMENT INFORMATION

The digital output stage of the TLC354 can be damaged if it is held in the linear region of the transfer curve. Conventional operational amplifier/comparator testing incorporates the use of a servo loop that is designed to force the device output to a level within this linear region. Since the servo-loop method of testing cannot be used, the following alternative for measuring parameters such as input offset voltage, common-mode rejection, etc., are offered.

To verify that the input offset voltage falls within the limits specified, the limit value is applied to the input as shown in Figure 1(a). With the noninverting input positive with respect to the inverting input, the output should be high. With the input polarity reversed, the output should be low.

A similar test can be made to verify the input offset voltage at the common-mode extremes. The supply voltages can be slewed as shown in Figure 1(b) for the V_{ICR} test, rather than changing the input voltages, to provide greater accuracy.

A close approximation of the input offset voltage can be obtained by using a binary search method to vary the differential input voltage while monitoring the output state. When the applied input voltage differential is equal but opposite in polarity to the input offset voltage, the output changes state.

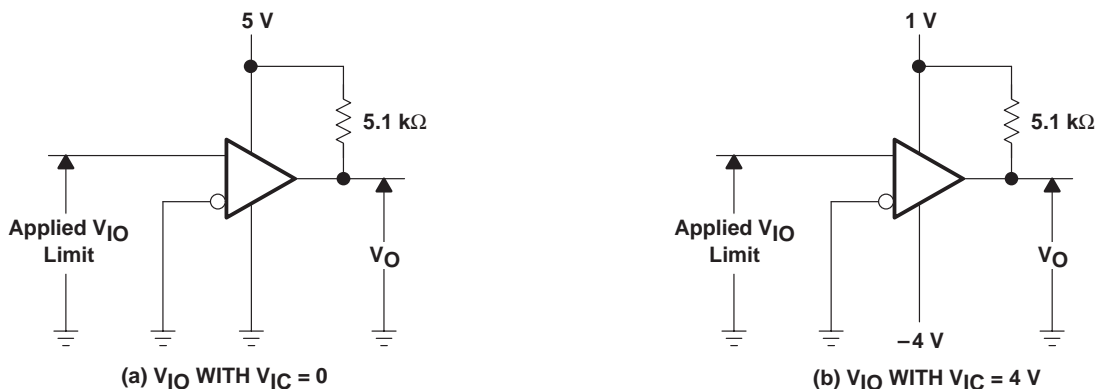


Figure 1. Method for Verifying That Input Offset Voltage is Within Specified Limits

PARAMETER MEASUREMENT INFORMATION

Figure 2 illustrates a practical circuit for direct dc measurement of input offset voltage that does not bias the comparator into the linear region. The circuit consists of a switching-mode servo loop in which U1a generates a triangular waveform of approximately 20-mV amplitude. U1b acts as a buffer with C2 and R4 removing any residual dc offset. The signal is then applied to the inverting input of the comparator under test, while the noninverting input is driven by the output of the integrator formed by U1c through the voltage divider formed by R9 and R10. The loop reaches a stable operating point when the output of the comparator under test has a duty cycle of exactly 50%, which can only occur when the incoming triangle wave is sliced symmetrically or when the voltage at the noninverting input exactly equals the input offset voltage.

Voltage divider R9 and R10 provides a step up of the input offset voltage by a factor of 100 to make measurement easier. The values of R5, R8, R9, and R10 can significantly influence the accuracy of the reading; therefore, it is suggested that their tolerance level be 1% or lower.

Measuring the extremely low values of input current requires isolation from all other sources of leakage current and compensation for the leakage of the test socket and board. With a good picoammeter, the socket and board leakage can be measured with no device in the socket. Subsequently, this open-socket leakage value can be subtracted from the measurement obtained with a device in the socket to obtain the actual input current of the device.

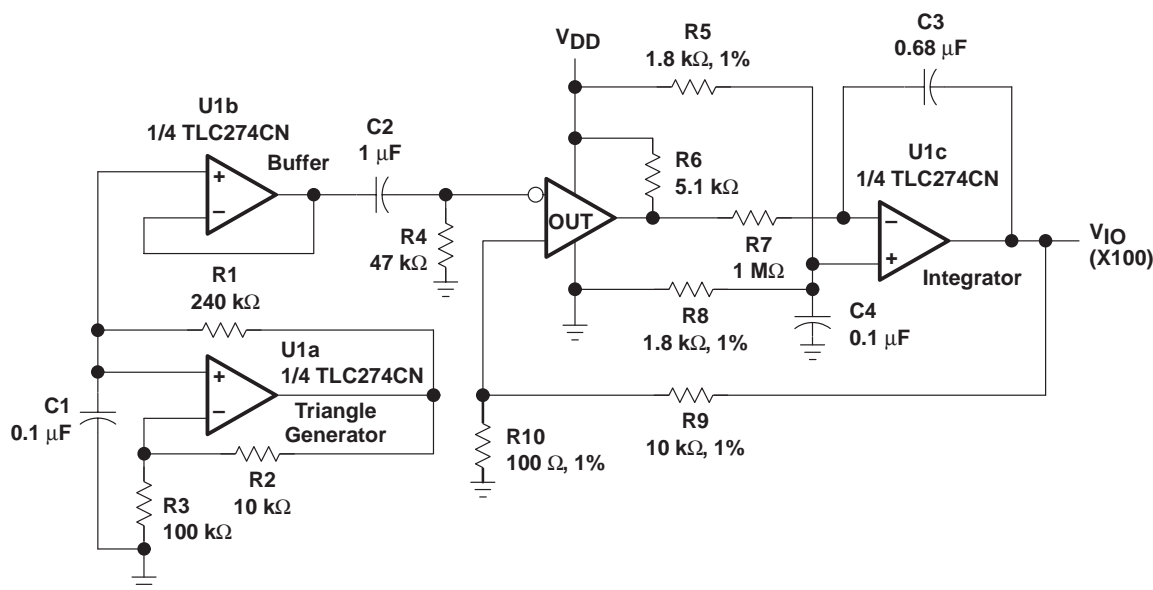
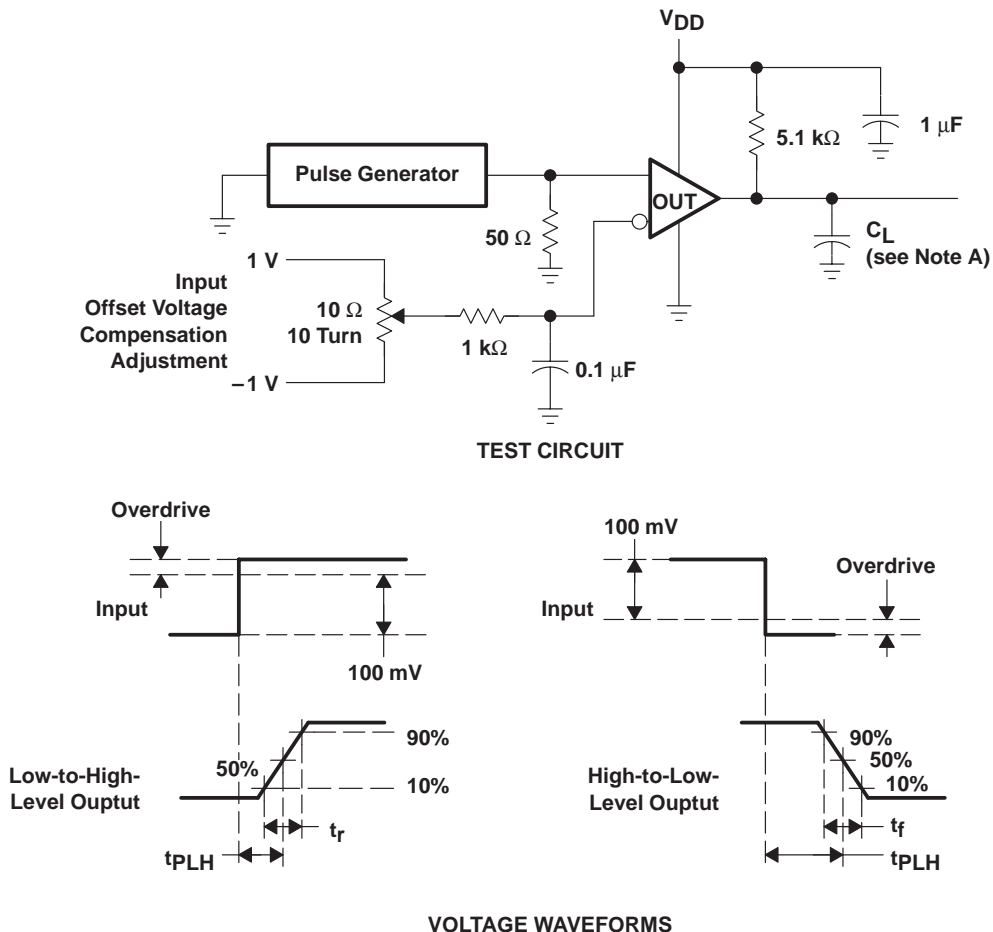


Figure 2. Test Circuit for Input Offset Voltage Measurement

PARAMETER MEASUREMENT INFORMATION

Response time is defined as the interval between the application of an input step function and the instant when the output reaches 50% of its maximum value. Response time, low-to-high-level output, is measured from the trailing edge of the input pulse. Response-time measurement at low input signal levels can be greatly affected by the input offset voltage. The offset voltage should be balanced by the adjustment at the inverting input (as shown in Figure 3) so that the circuit is just at the transition point. Then a low signal, for example, 105-mV or 5-mV overdrive, causes the output to change.



NOTE A: C_L includes probe and jig capacitance.

Figure 3. Response, Rise, and Fall Times Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC354CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC354C	Samples
TLC354CN	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC354CN	Samples
TLC354CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P354	Samples
TLC354CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P354	Samples
TLC354CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P354	Samples
TLC354ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC354I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC354CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC354CPWR	TSSOP	PW	14	2000	367.0	367.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

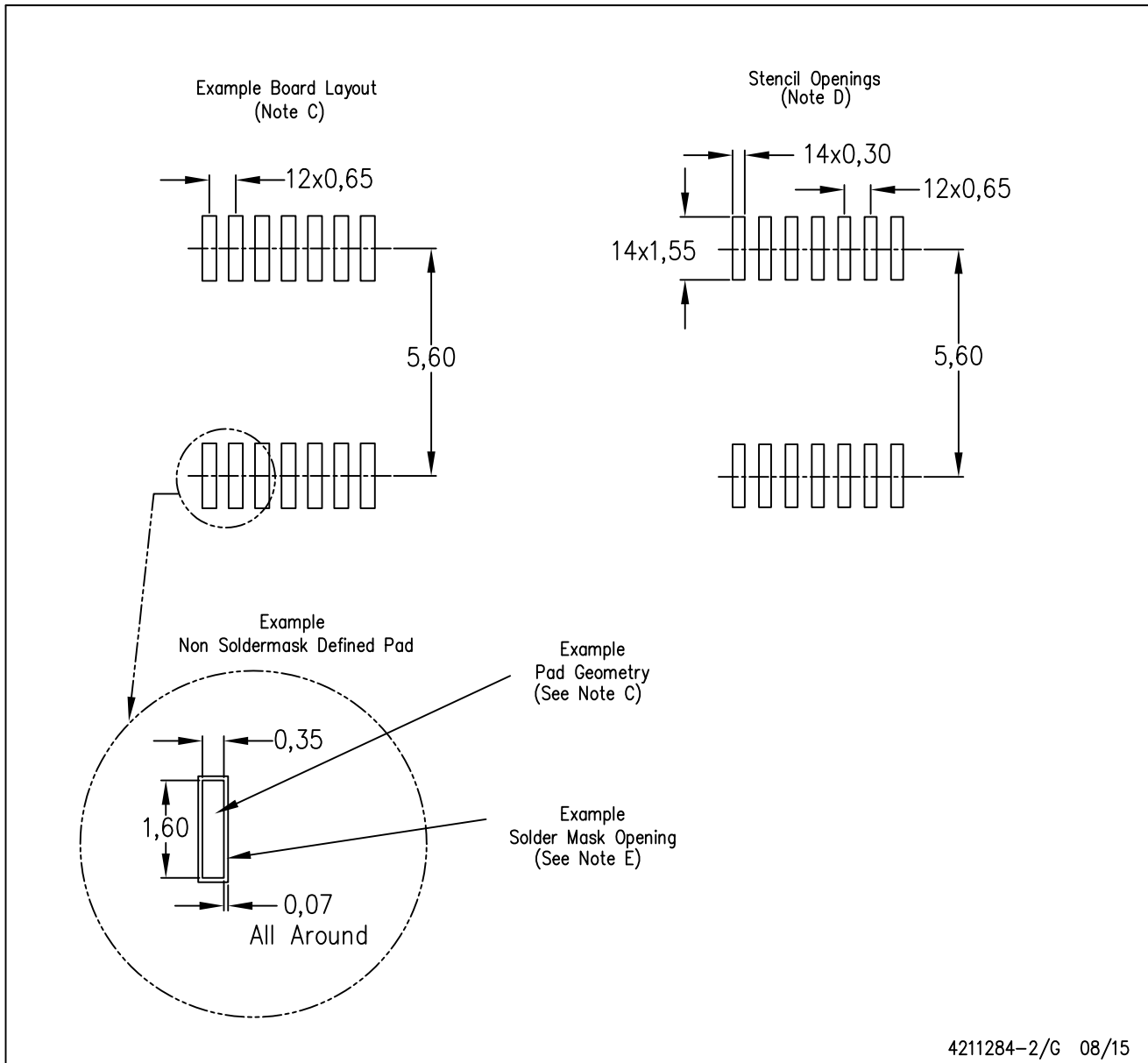


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View TLC354CD](#) on WIN SOURCE

 [Texas Instruments](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management